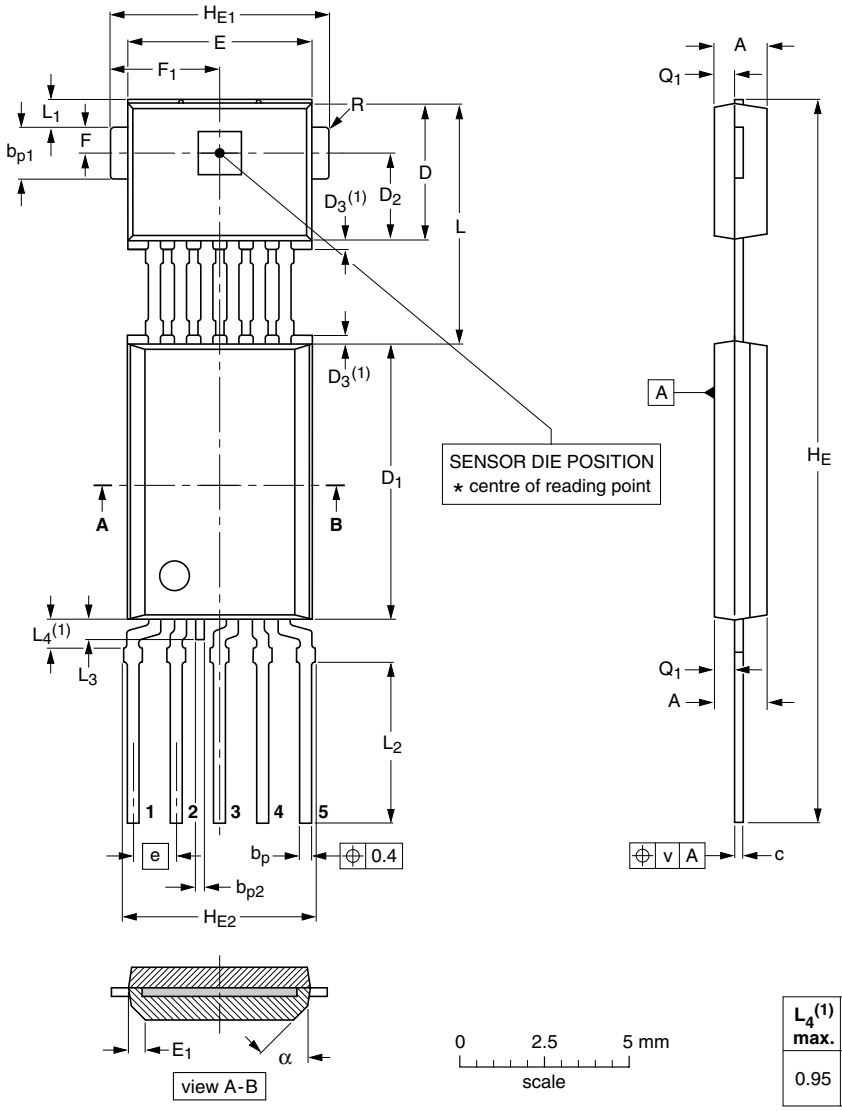
Package outline

Plastic single-ended multi-chip package; 6 interconnections; 5 in-line leads **SOT637**



L_4(1) max.	Q_1	R max.	v	α
0.95	0.65 0.55	0.2	1.2	45°

DIMENSIONS (mm are the original dimensions)

UNIT	A	b_p	b_{p1}	b_{p2}	c	D	D_1	D_2	D_3(1) max.	E	E_1	e	F	F_1	H_E	H_{E1}	H_{E2} max.	L	L_1	L_2 min.	L_3
mm	1.65 1.45	0.41 0.34	1.57 1.47	0.31 0.24	0.30 0.24	4.1 3.9	8.1 7.9	2.55	0.35	5.45 5.25	0.5	1.27	0.85 0.65	3.275 3.075	21.4 21.0	6.42 6.32	5.85	7.1 6.9	0.85 0.75	4.75	0.7 0.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic between and besides the leads.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT637						~~02-01-18~~ 04-12-10

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